



**THE DATASHEET OF
SN74BCT29843DWRG4**



SN74BCT29843

9-BIT BUS-INTERFACE D-TYPE LATCH WITH 3-STATE OUTPUTS

SCBS022C – FEBRUARY 1989 – REVISED NOVEMBER 1993

- BiCMOS Process With CMOS Inputs and TTL Outputs Substantially Reduces Standby Current
- Input Has 50 k Ω
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic 300-mil DIPs (NT)

description

The SN74BCT29843 features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

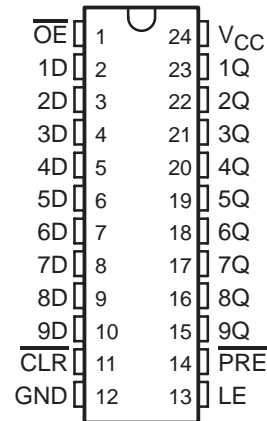
The nine latches are transparent D-type latches. When the latch-enable (LE) input is high, the Q outputs are complementary to the noninverting data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the nine outputs in either a normal logic state (high or low level) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pull-up components.

The output enable (\overline{OE}) does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The SN74BCT29843 is characterized for operation from 0°C to 70°C.

DW OR NT PACKAGE
(TOP VIEW)



FUNCTION TABLE

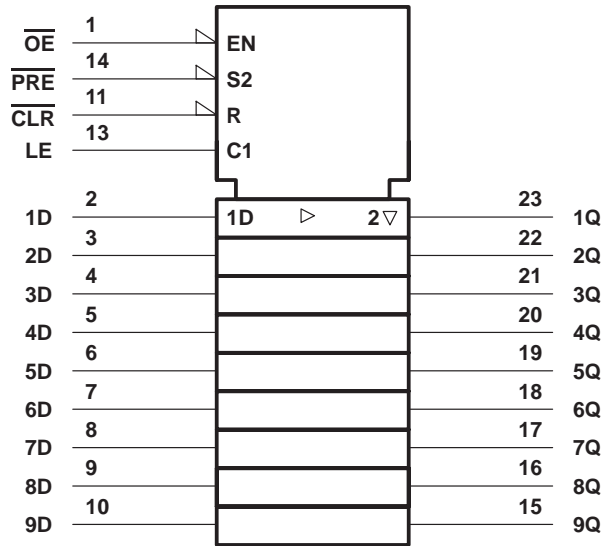
| INPUTS | | | | | OUTPUT |
|------------------|------------------|-----------------|----|---|----------------|
| \overline{PRE} | \overline{CLR} | \overline{OE} | LE | D | Q |
| L | X | L | X | X | H |
| H | L | L | X | X | L |
| H | H | L | H | L | L |
| H | H | L | H | H | H |
| H | H | L | L | X | Q ₀ |
| X | X | H | X | X | Z |

SN74BCT29843

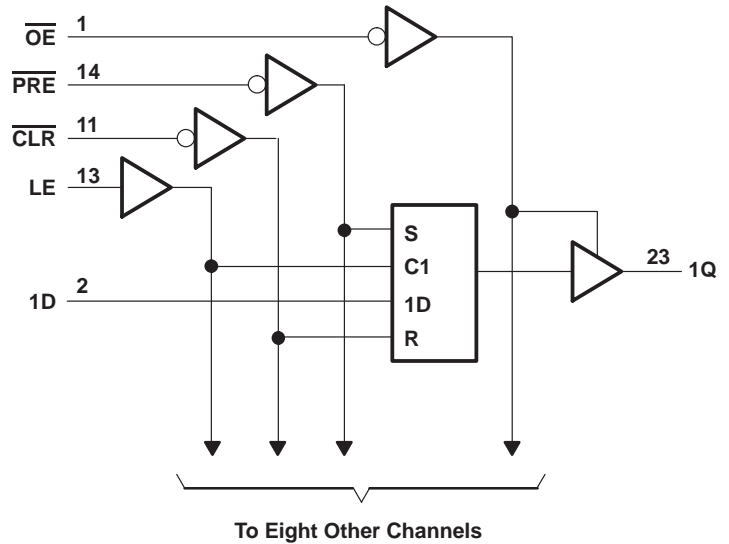
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logic symbol†



logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

| | |
|---|--------------------|
| Supply voltage range, V_{CC} | -0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | -0.5 V to 7 V |
| Voltage range applied to any output in the disabled or power-off state, V_O | -0.5 V to 7 V |
| Voltage range applied to any output in the high state, V_{OH} | -0.5 V to V_{CC} |
| Input clamp current, I_{IK} ($V_I < 0$) | -30 mA |
| Current into any output in the low state, I_{OL} | 96 mA |
| Operating free-air temperature range | 0°C to 70°C |
| Storage temperature range | -65°C to 150°C |

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the "recommended operating conditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions

| | | MIN | NOM | MAX | UNIT |
|----------|--------------------------------|-----|-----|-----|------|
| V_{CC} | Supply voltage | 4.5 | 5 | 5.5 | V |
| V_{IH} | High-level input voltage | 2 | | | V |
| V_{IL} | Low-level input voltage | | | 0.8 | V |
| I_{IK} | Input clamp current | | | -18 | mA |
| I_{OH} | High-level output current | | | -24 | mA |
| I_{OL} | Low-level output current | | | 48 | mA |
| T_A | Operating free-air temperature | 0 | | 70 | °C |



SN74BCT29843
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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | MIN | TYP† | MAX | UNIT |
|-----------|---------------------------|--------------------------|-----|------|------|---------------|
| V_{IK} | $V_{CC} = 4.5\text{ V}$, | $I_I = -18\text{ mA}$ | | | -1.2 | V |
| V_{OH} | $V_{CC} = 4.5\text{ V}$ | $I_{OH} = -15\text{ mA}$ | 2.4 | 3.2 | | V |
| | | $I_{OH} = -24\text{ mA}$ | 2 | | | |
| V_{OL} | $V_{CC} = 4.5\text{ V}$, | $I_{OL} = 48\text{ mA}$ | | 0.35 | 0.55 | V |
| I_I | $V_{CC} = 5.5\text{ V}$, | $V_I = 7\text{ V}$ | | | 0.1 | mA |
| I_{IH} | $V_{CC} = 5.5\text{ V}$, | $V_I = 2.7\text{ V}$ | -10 | | -75 | μA |
| I_{IL} | $V_{CC} = 5.5\text{ V}$, | $V_I = 0.4\text{ V}$ | | | -0.2 | mA |
| $I_{OS}‡$ | $V_{CC} = 5.5\text{ V}$, | $V_O = 0$ | -75 | | -275 | mA |
| I_{CCL} | $V_{CC} = 5.5\text{ V}$, | Outputs open | | 24 | 35 | mA |
| I_{CCH} | $V_{CC} = 5.5\text{ V}$, | Outputs open | | 3 | 7 | mA |
| I_{CCZ} | $V_{CC} = 5.5\text{ V}$, | Outputs open | | 3 | 7 | mA |

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| | | | MIN | MAX | UNIT |
|----------|---|---|-----|-----|------|
| t_w | Pulse duration | $\overline{\text{PRE}}$ low | 7 | | ns |
| | | $\overline{\text{CLR}}$ low | 5 | | |
| | | LE high | 4 | | |
| t_{su} | Setup time, data before $\text{LE}\downarrow$ | High or low | 1.5 | | ns |
| | | $\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ inactive | 2 | | |
| t_h | Hold time, data after $\text{LE}\downarrow$ | High or low | 3.5 | | ns |

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Note 2)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ | | | MIN | MAX | UNIT |
|-----------|-------------------------|-------------|---|-----|-----|-----|-----|------|
| | | | MIN | TYP | MAX | | | |
| t_{PLH} | \overline{D} | Q | 1.5 | 4.5 | 7 | 1.5 | 8 | ns |
| t_{PHL} | | | 1.5 | 5.7 | 8 | 1.5 | 9 | |
| t_{PLH} | LE | Q | 1.5 | 6 | 8 | 1.5 | 10 | ns |
| t_{PHL} | | | 1.5 | 6 | 8 | 1.5 | 10 | |
| t_{PLH} | $\overline{\text{PRE}}$ | Q | 1.5 | 6 | 8 | 1.5 | 12 | ns |
| t_{PHL} | | | 1.5 | 6 | 10 | 1.5 | 12 | |
| t_{PLH} | $\overline{\text{CLR}}$ | Q | 1.5 | 6 | 10 | 1.5 | 12 | ns |
| t_{PHL} | | | 1.5 | 6 | 10 | 1.5 | 12 | |
| t_{PZH} | $\overline{\text{OE}}$ | Q | 2 | 10 | 13 | 2 | 15 | ns |
| t_{PZL} | | | 2 | 10 | 13 | 2 | 15 | |
| t_{PHZ} | $\overline{\text{OE}}$ | Q | 2 | 5 | 7 | 2 | 8 | ns |
| t_{PLZ} | | | 2 | 5 | 7 | 2 | 8 | |

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|-------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| SN74BCT29843DW | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWE4 | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWE4 | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWE4 | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWG4 | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWG4 | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWG4 | ACTIVE | SOIC | DW | 24 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWR | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWR | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWR | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWRE4 | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWRE4 | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWRE4 | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWRE4 | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWRG4 | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWRG4 | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843DWRG4 | ACTIVE | SOIC | DW | 24 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74BCT29843NT | ACTIVE | PDIP | NT | 24 | 15 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74BCT29843NT | ACTIVE | PDIP | NT | 24 | 15 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74BCT29843NT | ACTIVE | PDIP | NT | 24 | 15 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74BCT29843NTE4 | ACTIVE | PDIP | NT | 24 | 15 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74BCT29843NTE4 | ACTIVE | PDIP | NT | 24 | 15 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN74BCT29843NTE4 | ACTIVE | PDIP | NT | 24 | 15 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74BCT29843DWR | SOIC | DW | 24 | 2000 | 330.0 | 24.4 | 10.75 | 15.7 | 2.7 | 12.0 | 24.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74BCT29843DWR | SOIC | DW | 24 | 2000 | 346.0 | 346.0 | 41.0 |

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